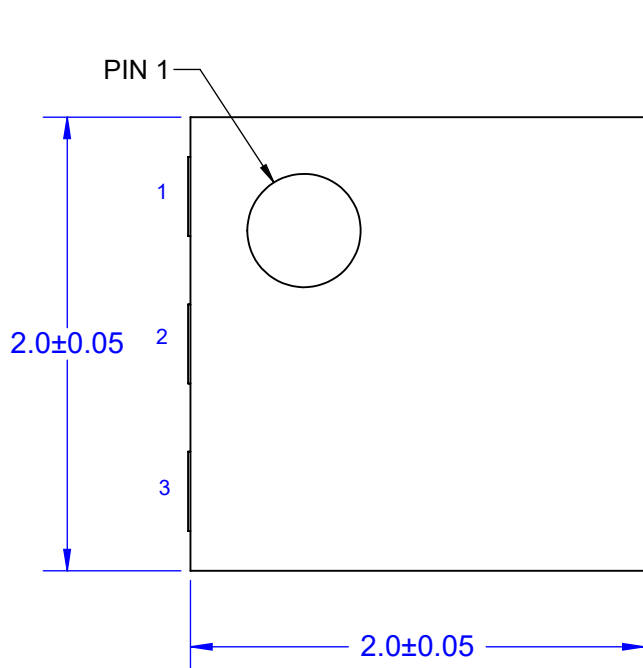
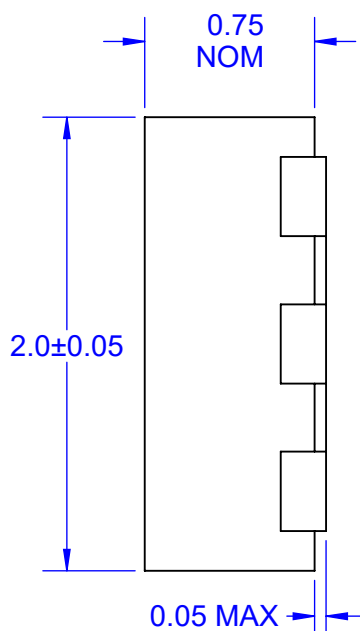


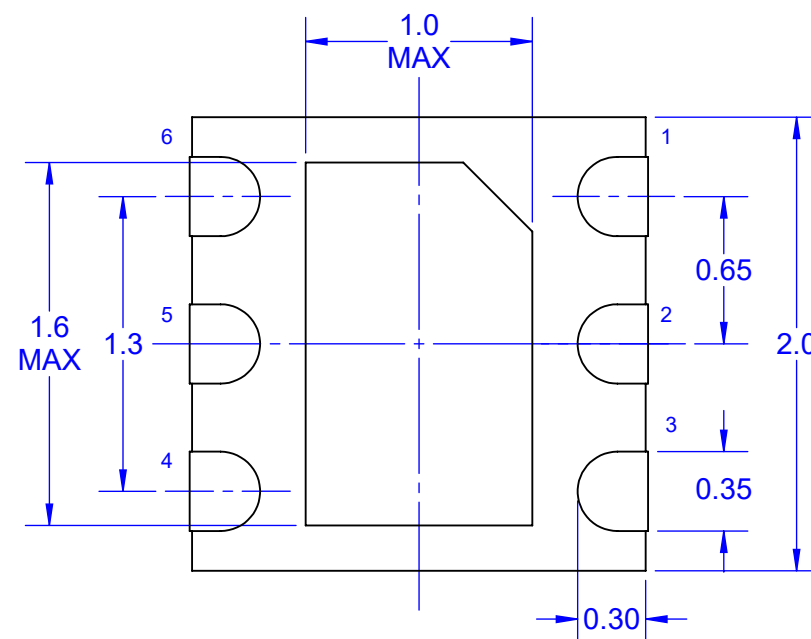
TOP VIEW



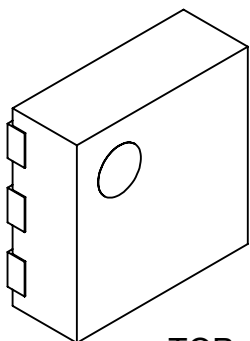
SIDE VIEW



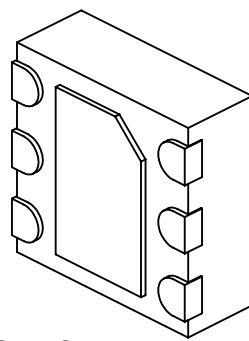
BOTTOM VIEW



MODEL



TOP



BOTTOM

Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: NiPdAu.
- 4) FRAME THICKNESS: 0.203mm.
- 5) DIE PAD: 1.6 x 1.0mm EXPOSED BOTTOM.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS IN mm.

APPROVALS	DATE	TopLine®			
DRAWN T.Au	11/6/2021				
ENG M. Hart	11/6/2021	TITLE 6-LEAD 2mm P0.65mm DFN DAISY CHAIN			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		15:1	A	460640	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

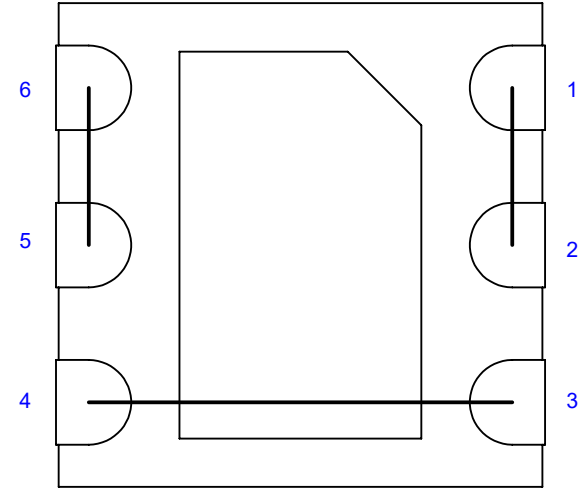
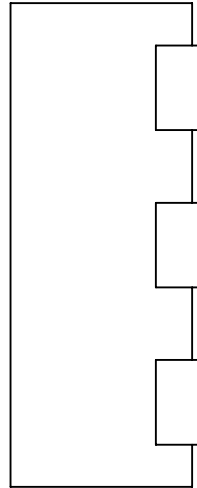
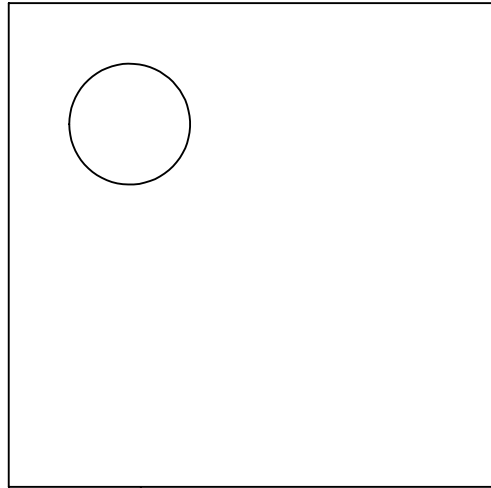
DAISY CHAIN PATTERN

TOP VIEW

SIDE VIEW

BOTTOM VIEW

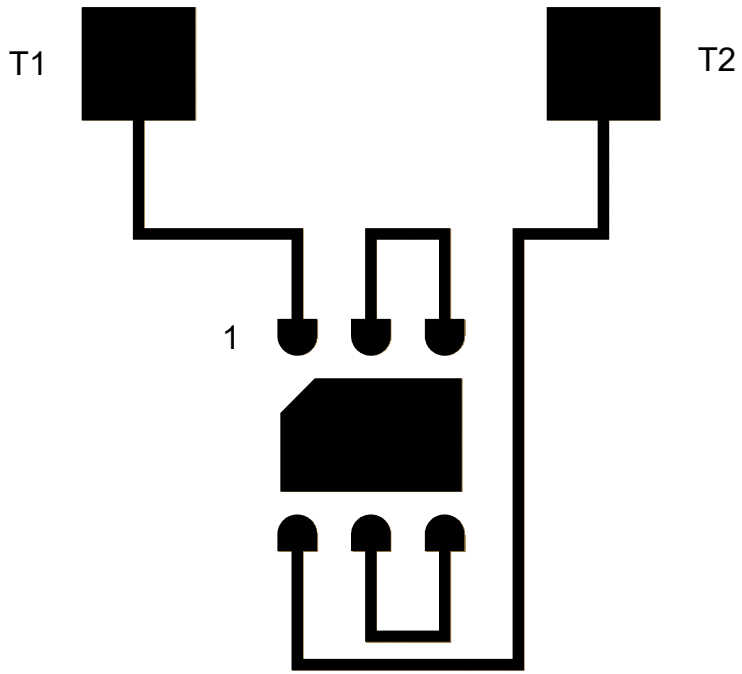
PIN 1



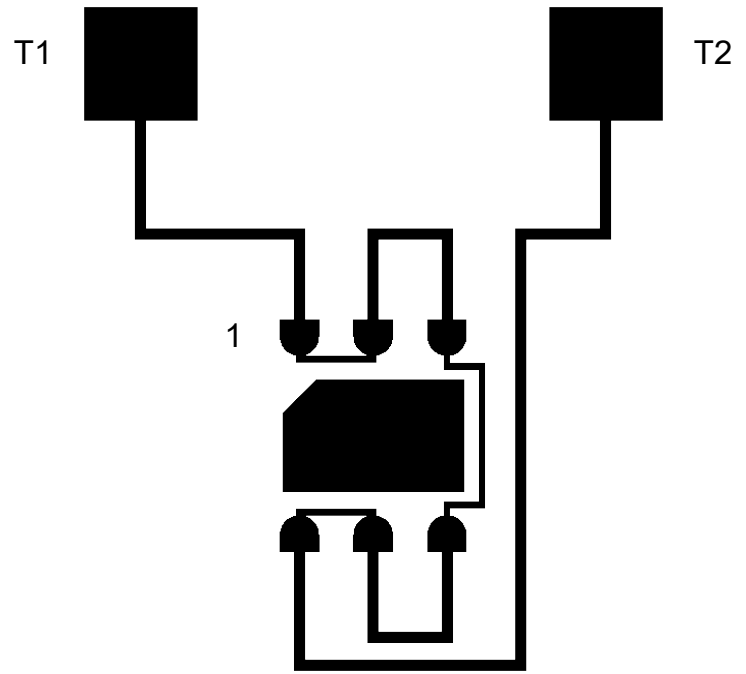
TOP SIDE ENCAPSULATION

NOTE:
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

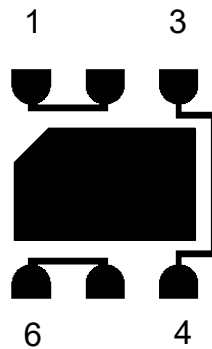
TopLine®			
TITLE 6-LEAD 2mm P0.65mm DFN DAISY CHAIN			
SCALE 16:1	SIZE A	DRAWING NO. 460640	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 5	



RECOMMENDED
PCB PADS



AFTER MOUNTING
ON PCB

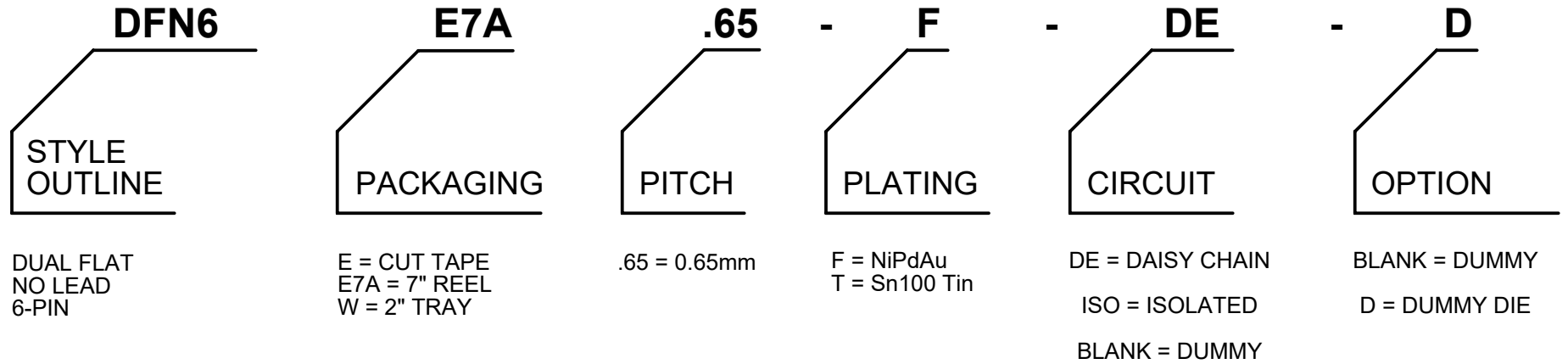


DFN

DAISY CHAIN NET LIST	
PINS	PINS
1 ~ 2	3 ~ 4
5 ~ 6	

TITLE		6-LEAD 2mm P0.65mm DFN DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	460640	A
DO NOT SCALE DRAWING			SHEET 3 OF 5

PART NUMBERING SYSTEM

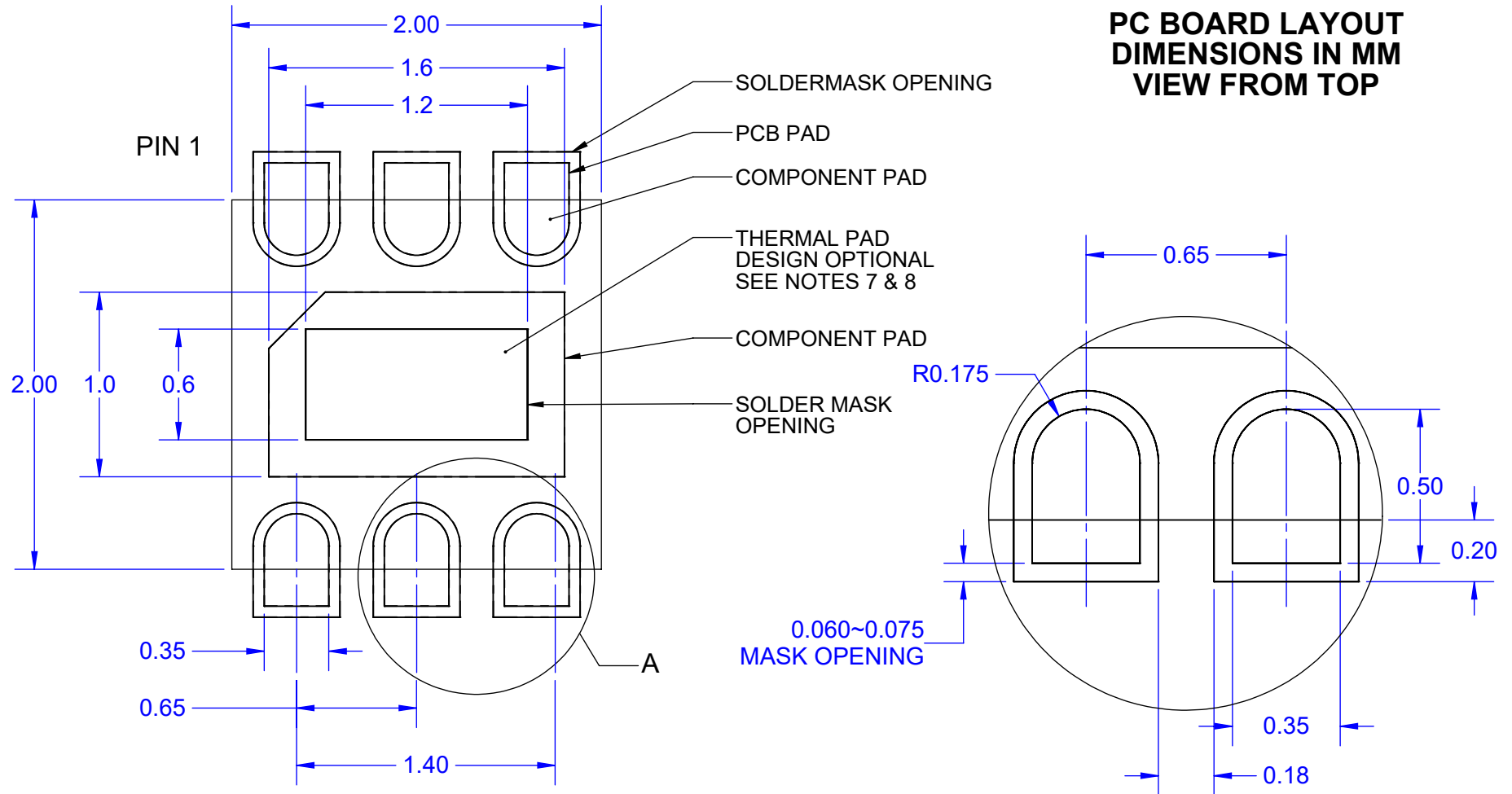


PART NUMBER	DAISY CHAIN	PACKAGING	RoHS Pb-FREE	MSL LEVEL	DUMMY DIE
DFN6E7A.65-F-DE-D	YES	REEL	YES	1	YES
DFN6E.65-F-DE-D	YES	CUT TAPE	YES	1	YES
DFN6W.65-F-DE-D	YES	2" TRAY WAFFLE PACK	YES	1	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

TopLine®			
TITLE 6-LEAD 2mm P0.65mm DFN DAISY CHAIN			
SCALE NONE	SIZE A	DRAWING NO. 460640	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 5

PC BOARD LAYOUT DIMENSIONS IN MM VIEW FROM TOP



DETAIL A
SCALE 50 : 1

Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
 - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
 - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
 - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

TopLine®			
TITLE 6-LEAD 2mm P0.65mm DFN DAISY CHAIN			
SCALE	SIZE	DRAWING NO.	REV
18:1	A	460640	A
DO NOT SCALE DRAWING			SHEET 5 OF 5